

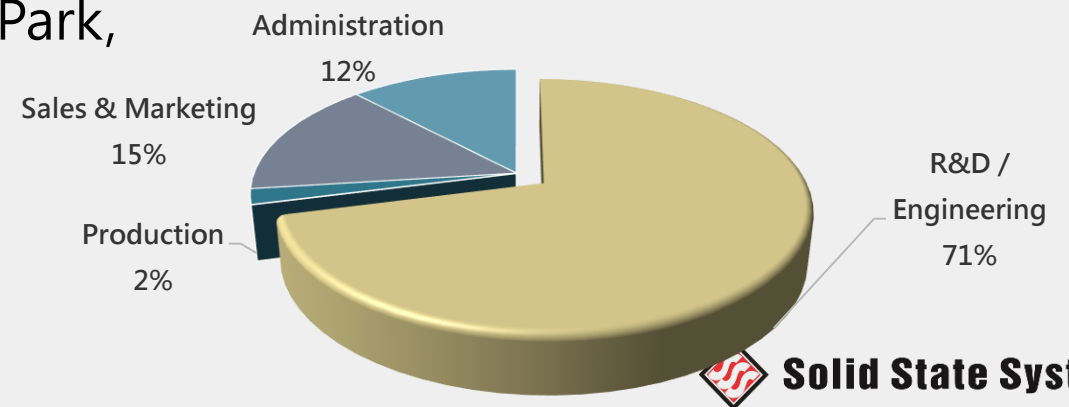
3S MEMS Microphone Introduction



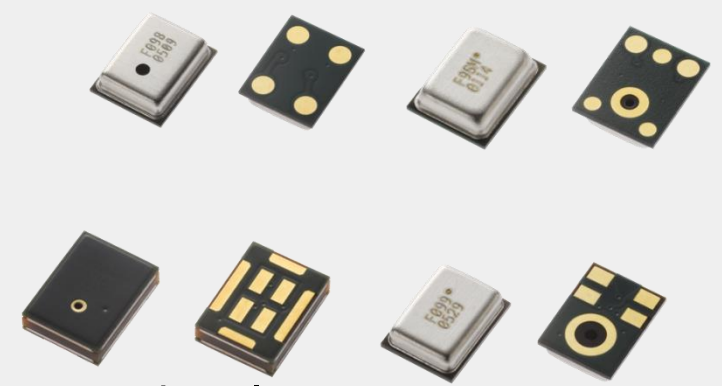
2022/11

3S Company Profile

- **Company Name** : Solid State System Co., Ltd.
- **Establish** : Nov. 1998
- **Chairman** : Jeffrey Lin
- **President** : Tim Hu
- **IPO Date** : Dec. 2007 (TPEX: 3259)
- **Capital** : US\$ 26.8 Million
- **Principal Institutional Shareholders** :
Kioxia (Formally Toshiba Memory), Kingston, UMC, PTI
- **Headquarters** : Tai Yuen Hi-Tech Industrial Park,
Hsinchu, Taiwan
- **Other Offices** : Shenzhen China
- **Employees** : 133



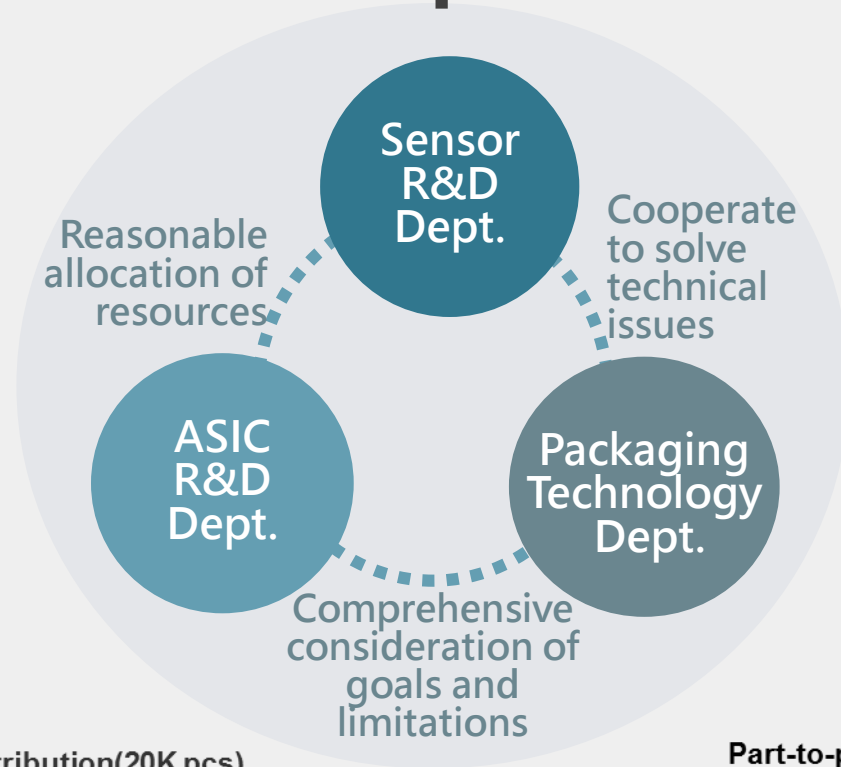
MEMS Mic Product Features



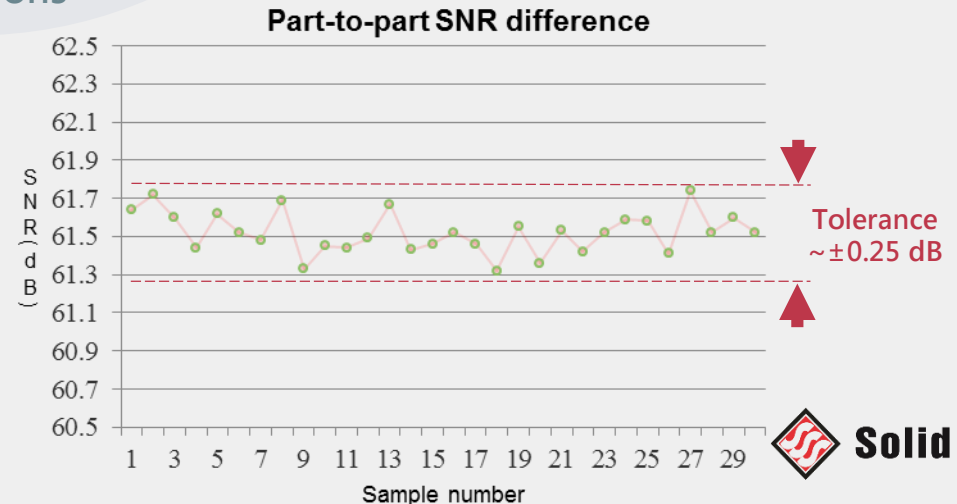
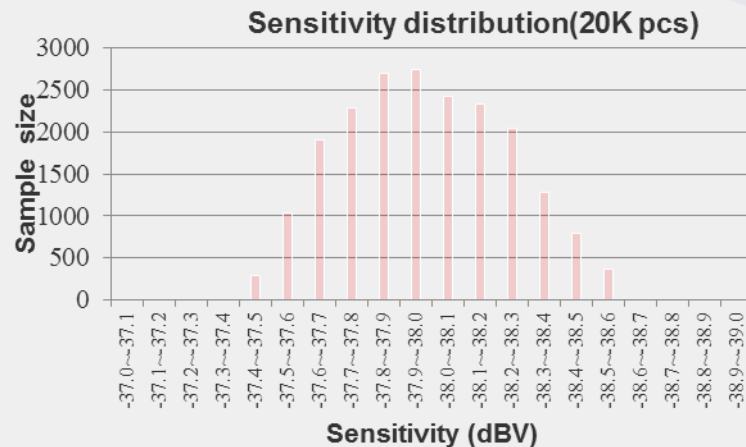
- **Patent Protection** : Patents cover all aspects of MEMS microphone technology.
- **Own Chips**: In-house designed MEMS sensor & pre-amp ASIC with foundry by UMC(Taiwan) and X-Fab(Malaysia), and packaged in Mainland China and Taiwan assembly houses.
- **100% Testing**: In-house developed testers for high throughput and high accuracy trimming/testing.
- **R&D Strength**: A well-experienced R&D team with 30+ years in-depth background in foundry, design house and package plant, plus key know-how and knowledge in MEMS structure, mix mode circuits and acoustic characteristics.
- **Application-oriented**: Continuous developing suitable MEMS sensors, pre-amp ASIC and packages to meet application specific real world requirements.
- **Supporting**: Experienced technical support team provides professional on-site support in design stage or production stage worldwide.

Advantages of Complete Solution Provider

A complete MEMS
Mic R&D team

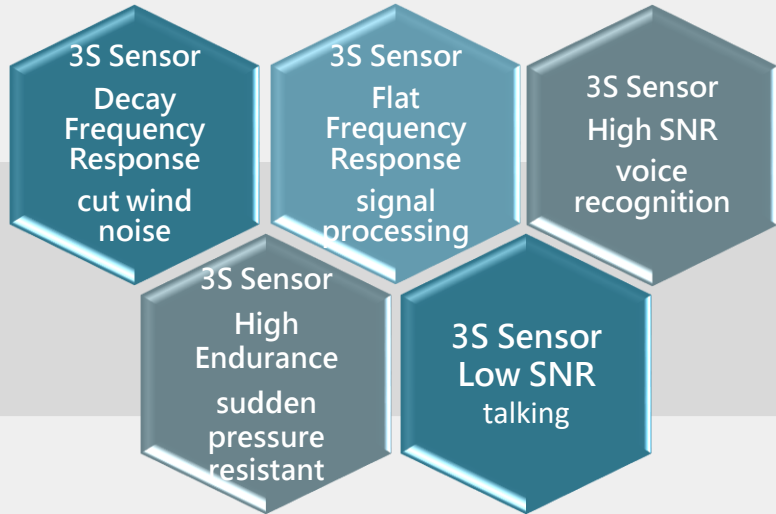


Product
Consistency ↑

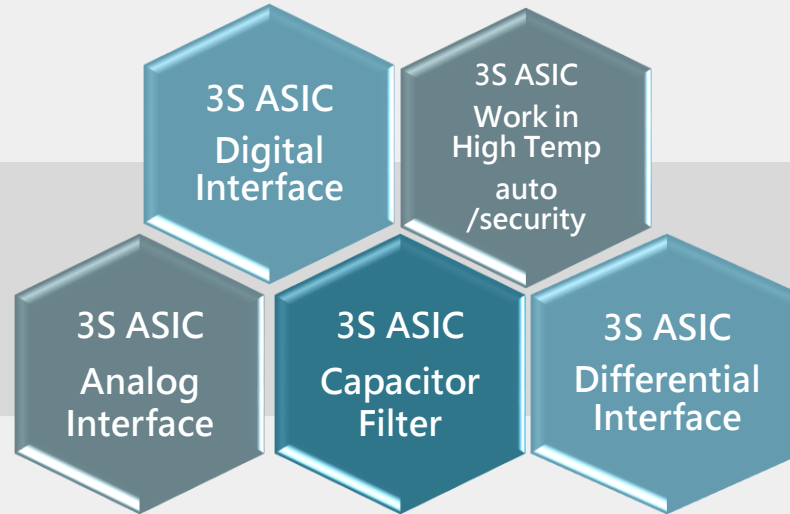


Advantages of Complete Solution Provider – 3S

Sensor Types

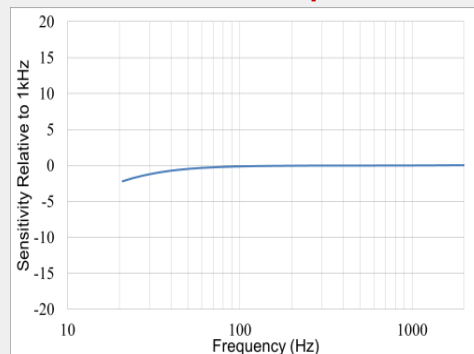
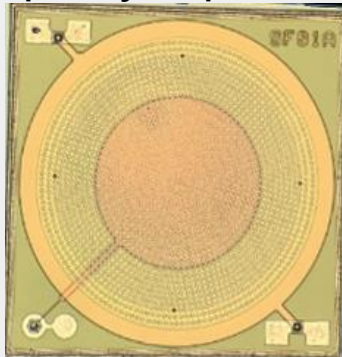


ASIC Types

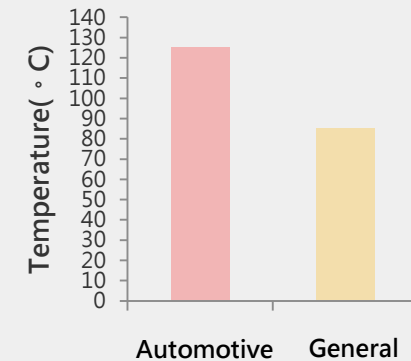
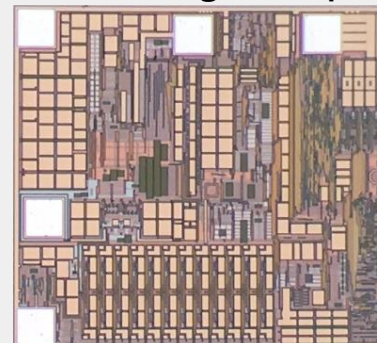


product features meet applications

flat frequency response → ANC headset · speech recognition



work in high temperature environment → automotive



Production Partners

Foundry



MIXED-SIGNAL FOUNDRY EXPERTS

X-FAB



UMC

Package



Forehope

(Package Capacity 10M/Month)



Lingsen

(Package Capacity 10M/Month)



WNX

(Package Capacity 6M/Month)

Testing

EVERLIGHT

EVERLIGHT



ITS



Solid State System

Own IP, Own IC, Own Patents

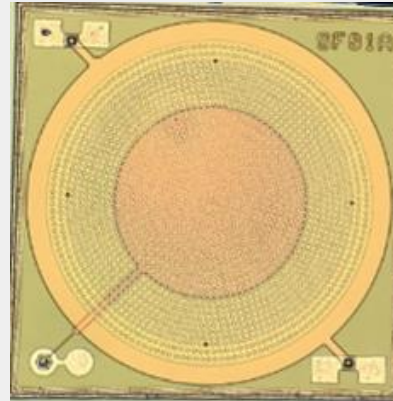
MEMS Patent

Patent

Structure

3S

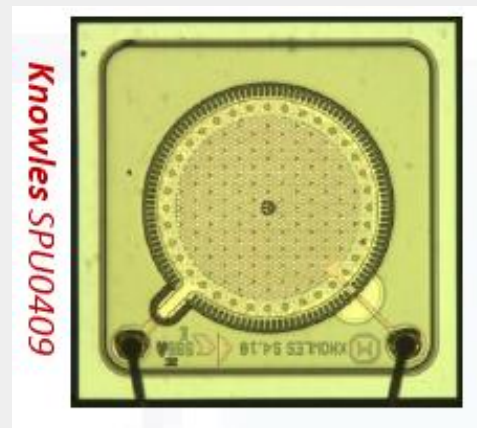
US8,093,119



3S' patented MEMS structure

Knowles

US6,535,460



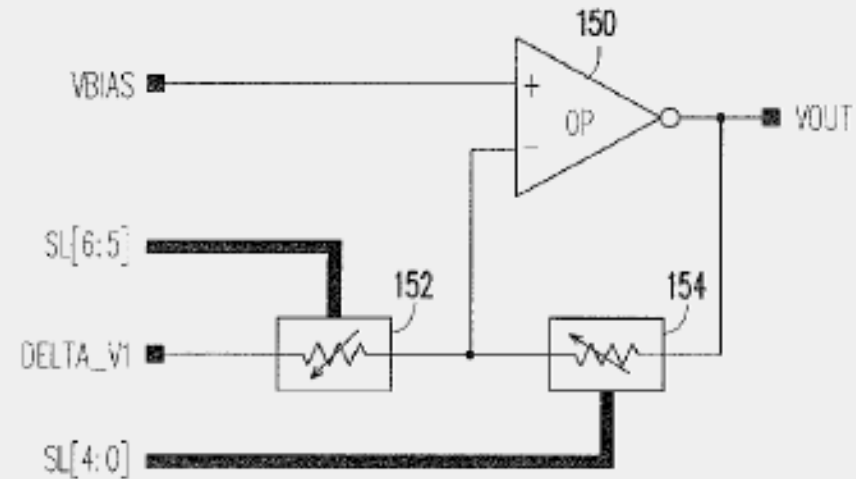
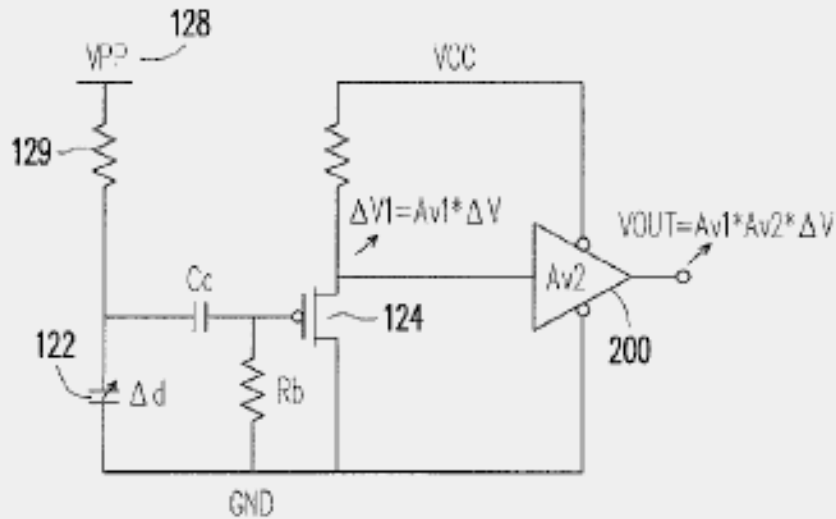
Knowles' patented MEMS structure

3S MEMS Mic Wafer Patent List

Patent number	Title	Category	Region
US7,795,063B2	Micro-electro-mechanical systems (mems) device and process for fabricating the same	Wafer	US
US7,951,636B2	Method for fabricating micro-electro-mechanical system (MEMS) device	Wafer	US
US8,030,112B2	Method for fabricating MEMS device	Wafer	US
US8,093,087B2	Method for fabricating MEMS device	Wafer	US
US8,093,119B2	CMOS microelectromechanical system (MEMS) device and fabrication method thereof	Wafer	US
US8,258,591B2	Micro-electro-mechanical systems (MEMS) device	Wafer	US
US8,464,589B2	Micro-electromechanical systems (MEMS) structure	Wafer	US
US8,502,329B2	Micro-electro-mechanical systems (MEMS) device and method for fabricating the same	Wafer	US
US8,673,732B2	Method for fabricating micro-electro-mechanical systems (MEMS) device	Wafer	US
US8,987,842B2	Microelectromechanical system (MEMS) device and fabrication method thereof	Wafer	US
US9,126,827B2	Microelectromechanical system (MEMS) device and fabrication method thereof	Wafer	US
US9,264,832B2	Microelectromechanical system (MEMS) microphone with protection film and MEMS microphonechips at wafer level	Wafer	US
US9,321,635B2	Method to release diaphragm in mems device	Wafer	US
CN101927977A	CMOS微机电系统(MEMS)装置的制造方法	Wafer	CN
CN102134054A	用于制造微机电系统装置的方法	Wafer	CN
CN102452635B	微机电系统结构	Wafer	CN
CN102963856B	微机电系统装置及其制造方法	Wafer	CN
CN103663345A	微型机电系统装置及其制造方法	Wafer	CN
CN104671195B	用于释放微机电系统装置中的隔膜的方法	Wafer	CN
I472474	微机电系统装置及其制造方法	Wafer	TW
I539827	微机电系统麦克风封装组件以及封装方法	Wafer	TW
I565333	用于释放微机电系统 (MEMS) 装置中的隔膜的方法	Wafer	TW
I594940	微机电系统麦克风	Wafer	TW

Trimming Patent

Patent number	Title	Category	Region
US8,094,839B2	Microelectromechanical system (MEMS) device with sensitivity trimming circuit and trimming process	Other	US
CN101877811B	具有灵敏度调整电路以及调整过程的微机电系统装置	Other	CN



3S pioneered and was granted a worldwide first US patent of trimming process for MEMS microphone.

3S MEMS Mic Other Patent List

Patent number	Title	Category	Region
US8,043,897B2	Method for forming micro-electro-mechanical system (MEMS) package	Package	US
US8,173,471B2	Method for fabricating micro-electro-mechanical system (MEMS) device	Package	US
US8,193,596B2	Micro-electro-mechanical systems (MEMS) package	Package	US
US8,217,474B2	Hermetic MEMS device and method for fabricating hermetic MEMS device and package structure of MEMS device	Package	US
US9,271,087B1	Microelectro-mechanical systems (MEMS) microphone package device and MEMS packaging method thereof	Package	US
CN101665230A	微机电系统封装及其形成方法	Package	CN
CN102107846B	密封微机电系统装置及其制造方法与封装结构	Package	CN
US8,094,839B2	Microelectromechanical system (MEMS) device with sensitivity trimming circuit and trimming process	Other	US
US8,934,649B2	Micro electro-mechanical system (MEMS) microphone device with multi-sensitivity outputs and circuit with the MEMS device	Other	US
CN101877811B	具有灵敏度调整电路以及调整过程的微机电系统装置	Other	CN
CN104591075B	保护微机电系统麦克风声音端口及其在芯片级形成的方法	Other	CN
CN104125533A	声音微组件测试装置与测试方法	Other	CN
I494548	声音微组件测试装置与测试方法	Other	TW
I516135	多级灵敏度输出的微机电系统麦克风装置及其电路	Other	TW

Applications

Applications



Mobile Phone



Notebook



TWS Headset



ANC Headset



Smart Speaker
/Audio Conference



TV



Surveillance/Intercom

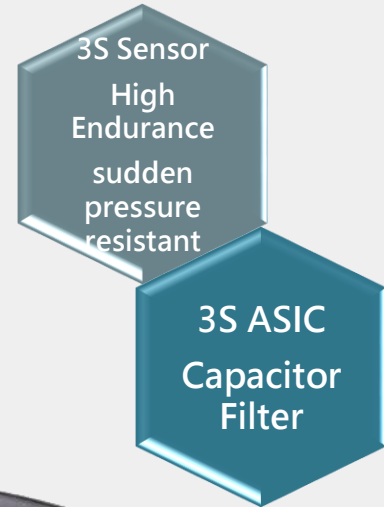


Automotive

Mobile Phone

Microphone selection guide

- High reliability requirements
- Microphone needs to resist air blowing at 85psi
- ASIC with capacitor filter to avoid RF interference
- Microphone are located closely to speaker due to the borderless screen. It requires high AOP 128dB



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM121JZB1VB-R	Analog	63 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	Mobile Phone

TWS Headset

Microphone selection guide

- Talking microphone requires sensitivity deviation +/-1dB
- Low current
- Small package size

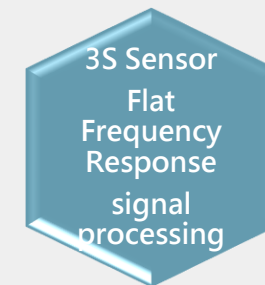


P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM123B4T1VA-R	Analog	56 dB	130 dB	-42±1 dBV	26 Hz	2.75 x 1.85 x 0.95mm	Top	TWS Headset
3SM123C4T1VA-R	Analog	57 dB	123 dB	-42±1 dBV	63 Hz	2.75 x 1.85 x 0.95mm	Top	
3SM122HZB1VD-R	Analog	62 dB	123 dB	-38±1 dBV	30 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM123GZB1VD-R	Analog	61.5 dB	123 dB	-38±1 dBV	20 Hz	2.75 x 1.85 x 0.90mm	Bottom	

ANC Headset

Microphone selection guide

- ANC Feedforward(FF) requires phase matching and flat low frequency response
- ANC Feedback(FB) requires high SNR 64dB, high AOP 128dB, **and flat frequency response for adaptive ANC**



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM122FZT1VA-002	Analog	60 dB	130 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.95mm	Top	ANC Feedforward(FF)
3SM122KZT1VA-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 1.05mm	Top	
3SM122KZB1VD-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM222FMT1WA	Digital	60 dB	120 dB	-26±1 dBFS	38 Hz	3.10 x 2.50 x 0.90mm	Top	
3SM222HMB1WA	Digital	62 dB	120 dB	-26±1 dBFS	<20 Hz	3.10 x 2.50 x 0.85mm	Bottom	
3SM222HMB1HA-002	Digital	62 dB	120 dB	-26±1 dBFS	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM122KZT1VA-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 1.05mm	Top	ANC Feedback(FB)
3SM122KZB1VD-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM121LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM121MZB1UA	Analog	66 dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 3.00 x 1.10mm	Bottom	
3SM121PZB1MB	Analog	68 dB	130 dB	-38±1 dBV	<20 Hz	4.72 x 3.76 x 1.20mm	Bottom	

Hearing Aids Application Series 3SM126

- Microphone Size : 2718 small package
- Electrical Characteristics
 - 1) Supply Voltage 1.6~3.6V
 - 2) Current consumption 80uA
- Product Characteristics
 - 1) MEMS is resistant to UV light interference
 - 2) ASIC adds filtering capacitors to avoid RF interference



Currently we present SNR 62dB Top-port product and SNR 64dB Top-port or Bottom Port will be followed

P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM126HZT1VC-R	Analog	62 dB	130 dB	-38±1 dBV	130 Hz	2.75 x 1.85 x 1.05mm	Top	Hearing Aids

Smart Speaker/Audio Conference



Microphone selection guide

- High phase and sensitivity consistency suitable for directional voice capture

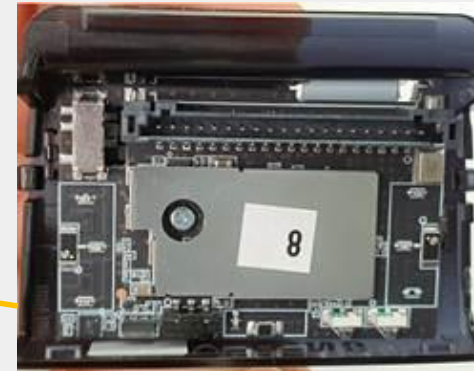
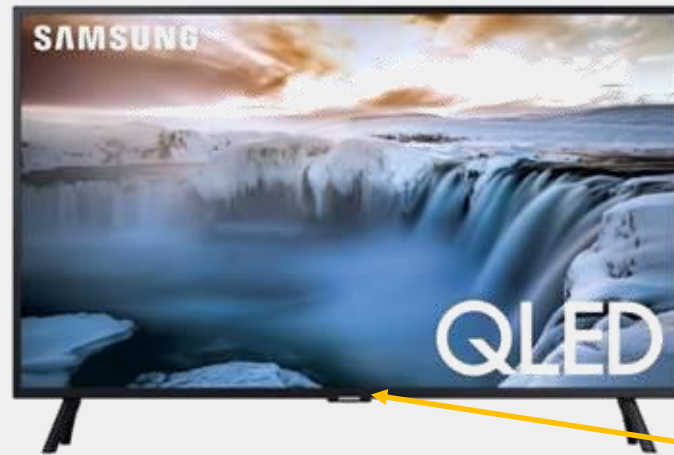


P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM121MZT1UA	Analog	66 dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 2.95 x 1.10mm	Top	Smart Speaker
3SM121MZB1UA	Analog	66 dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 3.00 x 1.10mm	Bottom	
3SM121PZB1MB	Analog	68 dB	130 dB	-38±1 dBV	<20 Hz	4.72 x 3.76 x 1.20mm	Bottom	
3SM121LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM221KMT1KA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 3.00 x 1.00mm	Top	
3SM222KMB1HA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	3.50 x 2.65 x 0.98mm	Bottom	

TV

Microphone selection guide

- High phase and sensitivity consistency suitable for directional voice capture



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM221KMT1KA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 3.00 x 1.00mm	Top	
3SM221KMT1GA-P	Digital	64 dB	120 dB	-26±1 dBFS	100 Hz	4.00 x 2.00 x 1.10mm	Top	TV
3SM222KMB1HA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	3.50 x 2.65 x 0.98mm	Bottom	

TV Remote Controller

Microphone selection guide

- Standard package

3S Sensor
High SNR
voice
recognition

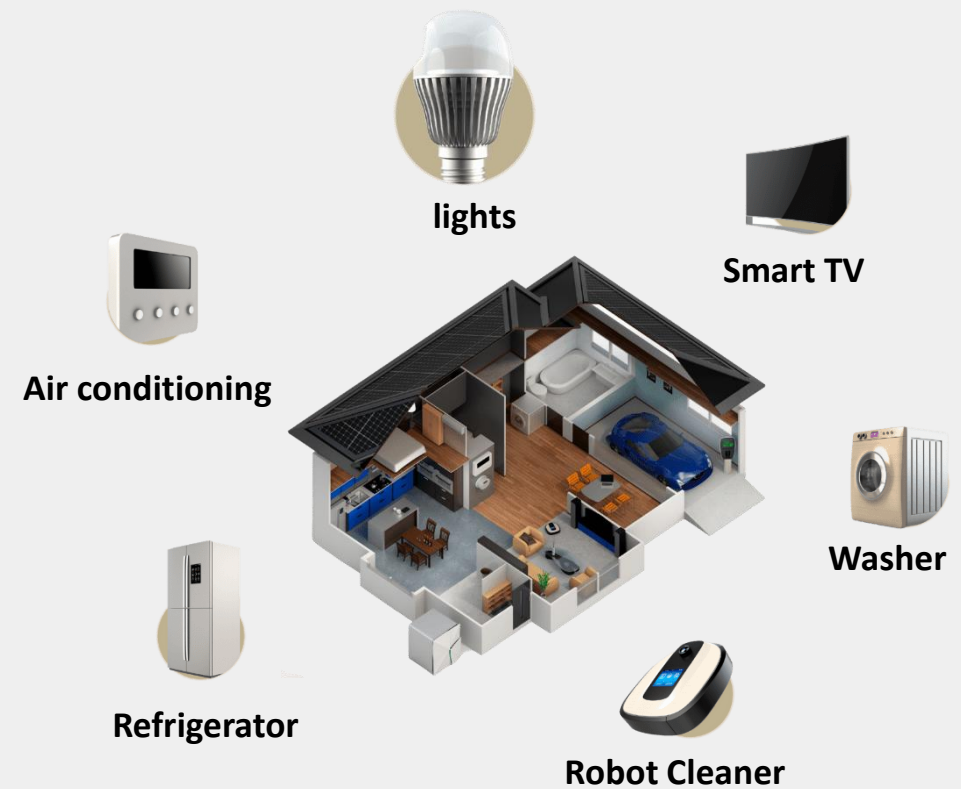


P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM121LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM121E4T1UB	Analog	59 dB	130 dB	-42±1 dBV	130 Hz	3.76 x 2.95 x 1.10mm	Top	TV Remote Controller
3SM121LZT1UB	Analog	65 dB	124 dB	-38±1 dBV	90 Hz	3.76 x 2.95 x 1.10mm	Top	

Smart Home

Microphone selection guide

- Meet the needs of the application
- High phase and sensitivity consistency are suitable for directional voice capture

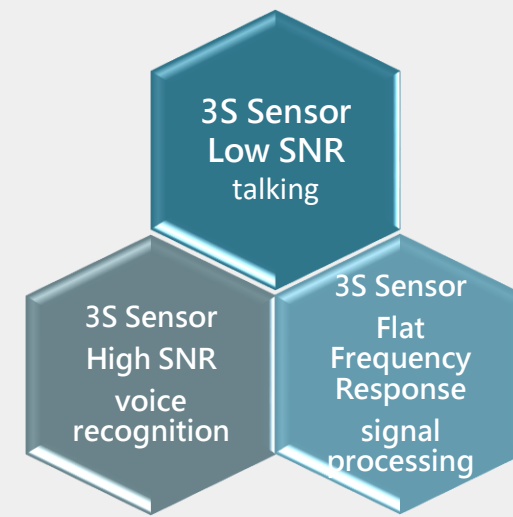
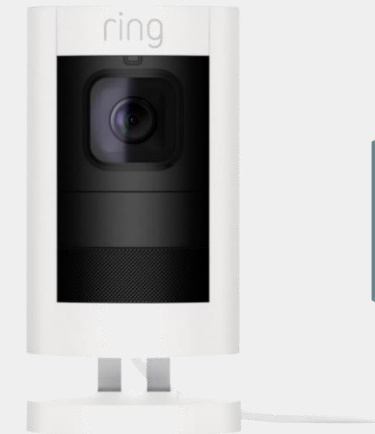


P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM123C4T1VA	Analog	57 dB	123 dB	-42±1 dBV	63 Hz	2.75 x 1.85 x 0.95mm	Top	Smart Home
3SM122KZT1VA	Analog	64 dB	128 dB	-38±1 dBV	30Hz	2.75 x 1.85 x 1.05mm	Top	
3SM123HZB1VD-002	Analog	62 dB	130 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM121LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM221KMT1KA	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 3.00 x 1.00mm	Top	
3SM222KMB1HA	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	3.50 x 2.65 x 0.98mm	Bottom	

Surveillance/Intercom

Microphone selection guide

- High SNR to support voice recognition
- Support ENC to have better speech quality. High phase consistency and flat low frequency response are required
- Low SNR to support general speech quality situation



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM121MZT1UA	Analog	66dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 2.95 x 1.10mm	Top	Voice Recognition
3SM121LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	Voice Recognition ENC
3SM122KZB1VD	Analog	64 dB	128 dB	-38±1 dBV	20 Hz	2.75 x 1.85 x 0.90mm	Bottom	ENC
3SM123C4T1VA-022	Analog	57dB	123 dB	-42±1 dBV	63 Hz	2.75 x 1.85 x 0.90mm	Top	General Speech Quality
3SM221KMT1KA	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 3.00 x 1.00mm	Top	Voice Recognition ENC
3SM222KMB1HA	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	3.50 x 2.65 x 0.98mm	Bottom	Voice Recognition ENC

Automotive

- Microphone selection guide
 - OE(Original Equipment) market temperature requirements (storage temperature: 150 °C / operating temperature: 125 °C)



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM127E4T1UB	Analog	59 dB	130 dB	-42±1 dBV	130 Hz	3.76 x 2.95 x 1.10mm	Top	DVR
3SM127F4T1UE	Analog	60 dB	130 dB	-42±1 dBV	<20 Hz	3.76 x 2.95 x 1.10mm	Top	BT voice call Speech Recognition ENC
3SM127MZT1UA	Analog	66 dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 2.95 x 1.10mm	Top	BT voice call Speech Recognition ENC ANC
3SM127MZB1UA	Analog	66 dB	130 dB	-38±1 dBV	<20 Hz	3.76 x 3.00 x 1.10mm	Bottom	
3SM127LZB1HA	Analog	65 dB	130 dB	-38±1 dBV	<20 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM227KMT1KA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 3.00 x 1.00mm	Top	DVR BT voice call Speech Recognition ENC ANC
3SM227KMB1HA-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	3.50 x 2.65 x 0.98mm	Bottom	Speech Recognition ANC

Automotive Product Series

- 3S always pays attention to market development and assesses that the aftermarket will not be able to meet consumer expectations. In 2018, 3S launched and continued to improve the product series. The differences between the series are explained as follows

Series	3SM121/122(Analog) 3SM222(Digital)	3SM127(Analog) 3SM227(Digital)
Target	AM	OE
characteristic	<ul style="list-style-type: none"> ■ Consumer grade packaging materials ■ Consumer grade reliability test 	<ul style="list-style-type: none"> ■ car-specific grade packaging materials ■ car-specific grade reliability test ■ Guarantee product life cycle ■ AEC-Q103 certification

※ The Automotive Electronics Council (AEC) is an organization originally established in the 1990s by Chrysler, Ford, and GM for the purpose of establishing common part-qualification and quality-system standards.

AEC-Q100 is Verification specification for active components
 AEC-Q103 is Verification specification for MEMS microphones

Notebook

Microphone selection guide

- High phase and sensitivity consistency suitable for directional voice capture
- Standard package



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM221KMT1KC-P	Digital	64 dB	120 dB	-26±1 dBFS	24 Hz	4.00 x 3.00 x 1.00mm	Top	Notebook
3SM221KMT1GC-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 2.00 x 1.10mm	Top	Notebook with Narrow Border

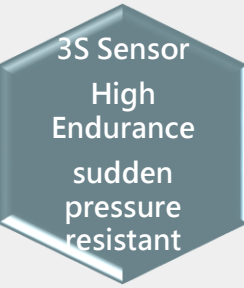
Wearable Devices

Microphone selection guide

- Low current
- Small package size



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Application
3SM123GZB1VD	Analog	61.5 dB	123 dB	-38±1 dBV	20 Hz	2.75 x 1.85 x 0.90mm	Bottom	Smart Watch
3SM222KMB1HC-P	Digital	64 dB	120 dB	-26±1 dBFS	30 Hz	3.50 x 2.65 x 0.98mm	Bottom	



Withstand Air Pressure Series

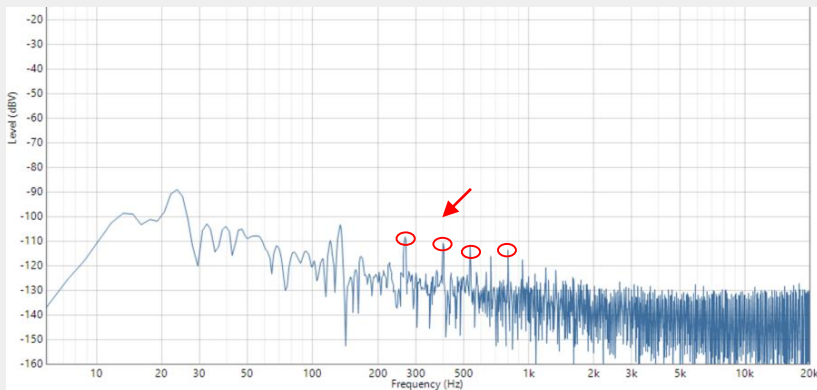
- MEMS particular structure design with ultra-high reliability can withstand sudden pressure up to 100Psi (6.8ATM)
 - ※Extremely static pressure will not cause damage to the mic membrane due to the balance of pressure on both sides
- Waterproof mechanical design can easily cause air pressure on the microphone membrane during case assembly. This MEMS series can improve the production yield rate.
- It can effectively reduce the microphone membrane damaged when there is a large airflow near the sound of hole during production or actual use
- This MEMS series can ensure product life span for outdoor device that continue to face strong winds



P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Feature
3SM222KMB1HC-P	Digital	64 dB	120 dB	-26±1 dBFS	30 Hz	3.50 x 2.65 x 0.98mm	Bottom	
3SM221KMT1KC-P	Digital	64 dB	120 dB	-26±1 dBFS	24 Hz	4.00 x 3.00 x 1.00mm	Top	High endurance for sudden pressure
3SM221KMT1GC-P	Digital	64 dB	120 dB	-26±1 dBFS	50 Hz	4.00 x 2.00 x 1.10mm	Top	
3SM121KZB1HC	Analog	64 dB	120 dB	-38±1 dBV	30 Hz	3.50 x 2.65 x 0.98mm	Bottom	

Anti-RF Interference Series(1/2)

- 3S adds filtering capacitors in ASIC circuit design. There are many ways to avoid interference and we adopt the most effective and lowest cost ways to add embedded capacitors in ASIC
- With mechanism space limitation applications like Smartphone, TWS headset, walkie-talkie, smart watch...and so on, it can reduce RF interference for customer
- Small wireless device contains multiple microphones and antenna. Due to the limitation of product size, we cannot ensure no RF interference in such short distance between microphones and antenna and cause noise sound
- The way to resist RF interference can start from circuit or mechanism design. Due to the various forms of RF interference, the design of filtering capacitors in the ASIC circuit can improve PCB layout and mechanism design flexibility.



Above, the MEMS microphone 3SM121HQB1VB-R is closely attached to the mobile phone antenna for calling test. There is no obvious prominent signal and the interference signal is within the allowable range.

Anti-RF Interference Series(2/2)

P/N	A/D	SNR	AOP	Sensitivity	LFRO	Package	Port	Feature
3SM123B4T1VA-R	Analog	56 dB	130 dB	-42±1 dBV	26 Hz	2.75 x 1.85 x 0.95mm	Top	
3SM123C4T1VA-R	Analog	57 dB	123 dB	-42±1 dBV	63 Hz	2.75 x 1.85 x 0.95mm	Top	
3SM122KZT1VA-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 1.05mm	Top	
3SM123GZB1VD-R	Analog	61.5 dB	123 dB	-38±1 dBV	20 Hz	2.75 x 1.85 x 0.90mm	Bottom	Embedded filtering capacitor
3SM121JZB1VB-R	Analog	63 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM122HZB1VD-R	Analog	62 dB	123 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	
3SM122KZB1VD-002-R	Analog	64 dB	128 dB	-38±1 dBV	<20 Hz	2.75 x 1.85 x 0.90mm	Bottom	



Main Customer

SKYWORTH oppo ANKER STAR-NET 星网锐捷 ABB 海康威视 HIKVISION

广汽集团 GAC GROUP 长安汽车 GEELY DFSK CHERY 长城汽车 上汽大通 MAXUS



Skullcandy JLABS HARMAN A SAMSUNG COMPANY JBL by HARMAN MASTER & DYNAMIC

PHILIPS KEF INNOVATORS IN SOUND ViewSonic

India boAt

Taiwan MSI LUXGEN

Japan HONDA Clarion audio-technica

Roadmap of Analog MEMS Microphone

2022	2023	2024
<p data-bbox="547 429 970 554">3SM121RZB1MB 4.72x3.76x1.20mm@Bottom SNR 70dB/AOP 127dB</p> <p data-bbox="772 576 1195 701">3SM421LZB1AA 3.35x2.50x0.98mm@Bottom SNR 65dB/AOP 130dB Differential interface</p> <p data-bbox="772 723 1195 848">3SM421LZB1HA 3.50x2.65x0.98mm@Bottom SNR 65dB/AOP 130dB Differential interface</p> <p data-bbox="784 896 1467 1219">Differential interface is used in mobile phones and smart applications, which can provide better wireless signal interference protection capabilities</p>	<p data-bbox="1549 429 1972 554">3.50x2.65x0.98mm@Bottom SNR 68dB/AOP 130dB</p> <p data-bbox="1549 586 2158 811">In the standard 3526 package size, provides higher SNR solution for smart applications.</p>	

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Roadmap of Digital MEMS Microphone

2022	2023	2024
<p data-bbox="203 711 626 833">3SM222FMB1VA 2.75x1.85x0.90mm@Bottom SNR 60dB/AOP 120dB</p> <p data-bbox="203 868 626 991">3SM222CMT1VA 2.75x1.85x1.00mm@Top SNR 57dB/AOP 120dB</p>	<p data-bbox="988 411 1411 534">3.50x2.65x0.98mm@Bottom SNR 67dB/AOP 120dB/Sen - 26dBFS</p> <p data-bbox="988 568 1411 691">3.50x2.65x0.98mm@Bottom SNR 65dB/AOP 128dB/Sen - 37dBFS</p> <p data-bbox="988 731 1589 953">In the standard 3526 package size, provides higher SNR solution for smart applications.</p>	<p data-bbox="1773 411 2196 534">3.50x2.65x0.98mm@Bottom SNR 68dB/AOP 120dB/Sen - 26dBFS</p>

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**THANK
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